

| | | | |
|--------------------------|--|-------------------------------------|---------------------|
| PCN Number: | 20190520000.0 | PCN Date: | May 21, 2019 |
| Title: | Datasheet for MSP430F5172, MSP430F5152, MSP430F5132, MSP430F5171, MSP430F5151, MSP430F5131 | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Change Type: | | | |
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design |
| <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Data Sheet |
| <input type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Material |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Materials |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Process |

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**MSP430F5172, MSP430F5152, MSP430F5132
MSP430F5171, MSP430F5151, MSP430F5131**

SLAS619Q – AUGUST 2010 – REVISED JULY 2018

Changes from May 10, 2016 to July 19, 2018

Page

| | |
|--|--------------------|
| • Changed entry for Body Size of DSBGA package in <i>Device Information</i> table | 2 |
| • Updated Section 3.1, Related Products | 7 |
| • Removed D and E dimension lines from the YFF pinout (for the package dimensions, see the <i>Mechanical Data</i> in Section 8)..... | 10 |
| • Updated the note that begins "If DVIO is not supplied by the same source as DVCC..." on Section 5.3, Recommended Operating Conditions | 14 |
| • Updated notes (1) and (2) and added note (3) in Section 5.32, Wake-up Times From Low-Power Modes and Reset | 34 |
| • Removed ADC10DIV from the formula for the TYP value in the second row of the $t_{CONVERT}$ parameter in Section 5.39, 10-Bit ADC, Timing Parameters , because ADC10CLK is after division | 40 |
| • Changed the MAX value of the t_{EN_CMP} parameter with Test Conditions of "CBPWRMD = 10" from 1.5 μ s to 100 μ s in Section 5.43, Comparator_B | 43 |
| • Corrected typo in TDHCLKTRIM maximum value (changed from 128 to 127) in Test Conditions in Section 5.45, Timer_D, Local Clock Generator Frequency | 45 |
| • Corrected the port and pin numbers for the "Data transmit" row in Table 6-5, BSL Functions | 54 |



**MSP430F5172, MSP430F5152, MSP430F5132
MSP430F5171, MSP430F5151, MSP430F5131**

SLAS619R – AUGUST 2010 – REVISED SEPTEMBER 2018

Changes from July 20, 2018 to September 20, 2018

Page

| | |
|---|---------------------|
| • Added typical conditions statements at the beginning of Section 5, Specifications | 14 |
| • Updated Section 7.4, Documentation Support | 101 |

The datasheet number will be changing.

| | | |
|--|--------------|------------|
| Device Family | Change From: | Change To: |
| MSP430F5172, MSP430F5152, MSP430F5132 MSP430F5171, MSP430F5151, MSP430F5131 | SLAS619P | SLAS619R |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MSP430F5131>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

| | | | |
|------------------|------------------|------------------|------------------|
| MSP430F5131IDA | MSP430F5131IDAR | MSP430F5131IRSBR | MSP430F5131IRSBT |
| MSP430F5131IYFFR | MSP430F5131IYFFT | MSP430F5132IDA | MSP430F5132IDAR |
| MSP430F5132IRSBR | MSP430F5132IRSBT | MSP430F5132IYFFR | MSP430F5132IYFFT |
| MSP430F5151IDA | MSP430F5151IDAR | MSP430F5151IRSBR | MSP430F5151IRSBT |
| MSP430F5151IYFFR | MSP430F5151IYFFT | MSP430F5152IDA | MSP430F5152IDAR |
| MSP430F5152IRSBR | MSP430F5152IRSBT | MSP430F5152IYFFR | MSP430F5152IYFFT |
| MSP430F5171IDA | MSP430F5171IDAR | MSP430F5171IRSBR | MSP430F5171IRSBT |
| MSP430F5171IYFFR | MSP430F5171IYFFT | MSP430F5172IDA | MSP430F5172IDAR |
| MSP430F5172IRSBR | MSP430F5172IRSBT | MSP430F5172IYFFR | MSP430F5172IYFFT |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|-----------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| WW PCN Team | PCN_ww_admin_team@list.ti.com |